

JP 000 U.S. PTO
10/036389

01/07/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10036389	FILING DATE 01/07/2002	CLASS 257	SUBCLASS	GAU 2811	EXAMINER
**APPLICANTS: Liu Cheng-Yi; Swan Johanna; Towle Steven;					
**CONTINUING DATA VERIFIED: <i>none yet</i>					
<p>BEST AVAILABLE COPY</p>					
**FOREIGN APPLICATIONS VERIFIED: <i>none yet</i>					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials		2207/12660			
TITLE : Thinned die integrated circuit package					

U.S. DEPT. OF COMM /PAT. & TM-PTO-435L (Rev. 12-91)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Application Examiner	
PREPARED FOR ISSUE			
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM
(Attached in pocket on right inside flap)